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OCT 09 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Ichitsubo

Application No.: 10/804,737

Filed: 3/18/2004

Examiner: Lewis, Monica

Art Unit: 2822

RESPONSECommissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

The Office Action rejected claims 1-9, 11, 14 and 19-20 under 35 U.S.C. 103(a) as unpatentable over U.S. Patent No. 6,642,617 (Kawai) in view of Riches and Wang. Claim 3 was rejected under 35 U.S.C. 103(a) as being unpatentable over Kawai in view of Riches, Wang and Lin. Claim 10 was rejected under 35 U.S.C. 103(a) as being unpatentable over Kawai in view of Riches, Wang, and *Electronic Packaging and Interconnection Handbook* by Charles A. Harper (Harper). Claims 12 and 13 were rejected under 35 U.S.C. 103(a) as being unpatentable over Kawai in view of Riches, Wang, *Microchip Fabrication* by Peter Van Zant (van Zant). Claims 15 and 16 were rejected under 35 U.S.C. 103(a) as being unpatentable over Kawai in view of Riches, MCE, Pohjonen (U.S. Patent No. 6,462,950). Claim 17 was rejected under 35 U.S.C. 103 (a) as being unpatentable over Kawai in view of Riches, Wang, Pohjonen and Van Zant. Claim 18 was rejected under 35 U.S.C. 103(a) as being unpatentable over Kawai in view of Riches, Wang, Apel (U.S. Patent No. 6,727,761).

The Section 103 Rejection

In regards to claim 1, the Office Action asserts that Kawai discloses the following: